25D1640

Silicon NPN epitaxial planar type darlington

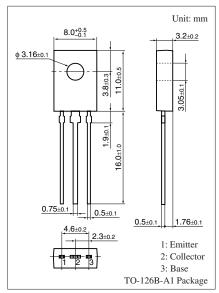
For low-frequency output amplification

■ Features

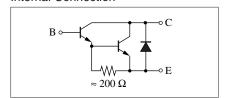
- High forward current transfer ratio hFE
- \bullet Large peak collector current $I_{\mbox{\footnotesize{CP}}}$
- High collector-emitter voltage (Base open) V_{CEO}

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	120	V	
Collector-emitter voltage (Base open)	V _{CEO}	100	V	
Emitter-base voltage (Collector open)	V_{EBO}	5	V	
Collector current	I_C	2	A	
Peak collector current	I_{CP}	3	A	
Collector power dissipation	P _C	1.2	W	
Junction temperature	T_{j}	150	°C	
Storage temperature	T_{stg}	-55 to +150	°C	



Internal Connection



\blacksquare Electrical Characteristics $T_a = 25 ^{\circ}C \pm 3 ^{\circ}C$

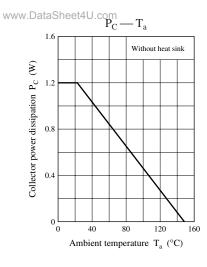
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_C = 100 \ \mu A, I_E = 0$	120			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = 1 \text{ mA}, I_B = 0$	100			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_E = 100 \mu\text{A}, I_C = 0$	5			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 25 \text{ V}, I_{E} = 0$			0.1	μΑ
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = 4 \text{ V}, I_C = 0$			1	μΑ
Forward current transfer ratio *1, 2	h _{FE}	$V_{CE} = 10 \text{ V}, I_{C} = 1 \text{ A}$	4000		40 000	_
Collector-emitter saturation voltage *1	V _{CE(sat)}	$I_C = 1.0 \text{ A}, I_B = 1.0 \text{ mA}$			1.5	V
Base-emitter saturation voltage *1	V _{BE(sat)}	$I_C = 1.0 \text{ A}, I_B = 1.0 \text{ mA}$			2.0	V

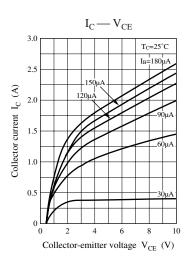
 $Note) \ 1. \ Measuring \ methods \ are \ based \ on \ JAPANESE \ INDUSTRIAL \ STANDARD \ JIS \ C \ 7030 \ measuring \ methods \ for \ transistors.$

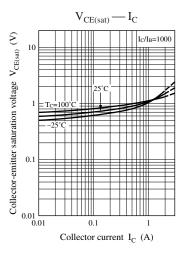
2. *1: Pulse measurement

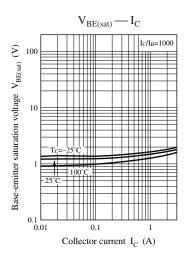
*2: Rank classification

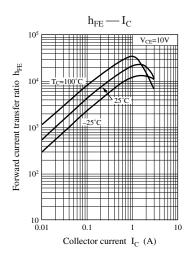
Rank	Q	R	S
h_{FE}	4000 to 10000	8 000 to 20 000	16 000 to 40 000

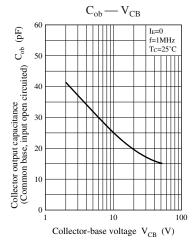


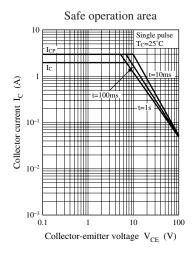


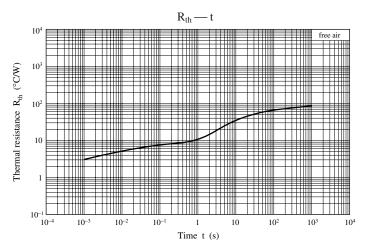












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